Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	6	("5027191"|"6483187"|"6525942").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/06 11:49
S2	4	("6020629"|"6528882").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/06 11:49
S3	9	("4835598" | "5130771" | "5640048" | "5959356" | "6206997" | "6282094" | "6325272").PN. OR ("6528882").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/06 11:50
S4	27	("5285352" | "5583377" | "5642261" | "5741729" | "5825628" | "5942795" | "5959356" | "6008536" | "6023098" | "6034427" | "6038137" | "6117705" | "6125042").PN. OR ("6282094").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/06 11:50
S5	9	("5027191" | "5710459" | "5741729" | "6212076" | "6282094" | "6483187" | "6525942" | "6657864" | "6882537").PN. OR ("6954360").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/06 11:51
S6	6	S5 not S1	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/06 11:51
S7	9	("5027191" | "5710459" | "5741729" | "6212076" | "6282094" | "6483187" | "6525942" | "6657864" | "6882537").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/06 14:13
S8	0	(3061/704).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/06 14:13
S9	2610	(361/704).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/06 14:20
S10	108	S9 and die with pad	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/06 14:23

S11	513	(257/670).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/06 14:23
S12	16888	pad with finger	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/06 15:22
S13	47	S11 and pad with finger	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/06 14:30
S14	9273	(257/66$1).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/06 15:19
S15	308	S14 and pad near5 finger	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/06 14:57
S16	284	S15 not S13	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/06 14:30
S17	234	S15 not S13	USPAT	OR	ON	2006/02/06 14:30
S18	54	("5479050" | "5594234" | "5663597").PN. OR ("6211462"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/06 14:40
S19	8251	(257/67$1).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/06 15:20
S20	340	S19 and pad near5 finger	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/06 14:57

S21	171	S20 not S15	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/06 14:57
S22	16888	pad with finger	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/06 15:19
S23	10981	pad near5 finger	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/06 15:21
S24	8251	S19 S11	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/06 15:20
S25	340	S24 and S23	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/06 15:22
S26	0	S25 not (S21 S18 S16 S15)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/06 15:22
S27	7064	pad near5 tip	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/06 15:21
S28	696	S27 and S23	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/06 15:22
S29	665	S28 not (S21 S18 S16 S15)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/06 16:28

S30	6241	S27 not S12	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/06 15:23
S31	167	S24 and S30	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/06 15:23
S32	167	S31 not (S21 S18 S16 S15)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/06 16:15
S33	2351	(IC chip die integrated near1 circuit semiconductor siliocn) near2 pad near5 (phalange thumb tip finger tip)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/06 16:17
S34	1976	S33 not S24	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/06 16:18
S35	2005	(IC chip die integrated near1 circuit semiconductor siliocn) near2 pad near4 (phalange thumb tip finger tip)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/06 16:32
S36	1673	S35 not S24	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/06 16:18
S37	629	(IC chip die integrated near1 circuit semiconductor siliocn) near1 pad with (extend$3 attach$3 prolong$3) with (phalange thumb tip finger tip)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/06 16:21
S38	14388	((IC chip die integrated near1 circuit semiconductor siliocn) near1 pad). ab.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/06 16:21

S39	252	S37 and S38	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/06 16:27
S40	202	S39 not (S21 S18 S16 S15 S32)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/06 16:22
S41	130	S39 and (PCB board BGA)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/06 16:35
S42	103	S41 not (S21 S18 S16 S15)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/06 16:33
S43	471	((IC chip die integrated near1 circuit semiconductor siliocn) near2 pad near4 (phalange thumb tip finger tip)).ab.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/06 17:04
S44	362	S43 not (S40 S21 S18 S16 S15)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/06 16:34
S45	1	S41 and S44	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/06 16:34
S46	80	S44 and (PCB board BGA)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/06 16:40
S47	1360	((IC chip die integrated near1 circuit semiconductor siliocn) with pad with (phalange thumb tip finger tip))	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/06 16:38
S48	836	((IC chip die integrated near1 circuit semiconductor siliocn) near2 pad with (phalange thumb tip finger tip))	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/06 16:39

S49	1793943	((IC chip die integrated near1 circuit semiconductor siliocn) near1pad with (phalange thumb tip finger tip))	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/06 16:39
S50	570	((IC chip die integrated near1 circuit semiconductor siliocn) near1 pad with (phalange thumb tip finger tip))	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/06 17:04
S51	373	S50 not S44	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/06 16:40
S52	76	S50 and (PCB board BGA)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/06 16:40
S53	12	("4362899" | "4890155" | "5194833").PN. OR ("5373187"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/06 16:45
S54	183	(IC chip die integrated near1 circuit semiconductor siliocn) near2 pad same PWB	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/06 17:04
S55	0	((IC chip die integrated near1 circuit semiconductor siliocn) near1 pad with (phalange thumb tip finger tip)) same PWB	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/06 17:05
S56	23	((IC chip die integrated near1 circuit semiconductor siliocn) near1 pad with (phalange thumb tip finger tip)) same PWB	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/06 17:05
S57	25	("4551746" | "4551747" | "5089881" | "5218230" | "5513076").PN. OR ("5691568").URPN.	US-PGPUB; USPAT; USOCR	OR ·	ON	2006/02/06 17:08
S58	54	("5519576" | "5672909" | "5691568").PN. OR ("5903050"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/06 17:16

S59	297	("20010008305" | "20010014538" |	US-PGPUB;	OR	ON	2006/02/06 17:25
		"20020011654" | "20020027297" |	USPAT;			
		"20020140061" | "20020140068" |	USOCR			
		"20020163015" | "20030030131" |				
		"20030073265" | "2596993" |				
		"3435815" | "3734660" | "3838984" |				
		"4054238" | "4189342" | "4258381" |				
		"4289922" | "4301464" | "4332537" |				
		"4417266" | "4451224" | "4530152" |				
		"4541003" | "4646710" | "4707724" |				
		"4727633" | "4737839" | "4756080" |				
		"4812896" | "4862245" | "4862246" |				
		"4907067" | "4916519" | "4920074" |				
		"4935803" | "4942454" | "4987475" |				
		"5018003" | "5029386" | "5041902" |				
		"5057900" | "5059379" | "5065223" |				
		"5070039" | "5087961" | "5091341" |				
		"5096852" | "5118298" | "5151039" |				
		"5157475" | "5157480" | "5168368" |				
		"5172213" | "5172214" | "5175060" |				
		"5200362" | "5200809" | "5214845" |				
		"5216278" | "5218231" | "5221642" |				
		"5250841" | "5252853" | "5258094" |				
		"5266834" | "5273938" | "5277972" |				
		"5278446" | "5279029" | "5281849" |				
		"5294897" | "5327008" | "5332864" |				
		"5335771" | "5336931" | "5343076" |				
		"5358905" | "5365106" | "5381042" |				
		"5391439" | "5406124" | "5410180" |				
		"5414299" | "5424576" | "5428248" |				
		"5435057" | "5444301" | "5452511" |				
		"5454905" | "5474958" | "5484274" |				
		"5493151" | "5508556" | "5517056" |				
		"5521429" | "5528076" | "5534467" |				
		"5539251" | "5543657" | "5544412" |				
		"5545923" | "5581122" | "5592019" |				
		"5592025" | "5594274" | "5595934" |				
		"5604376" | "5608265" | "5608267" |				
		"5625222" | "5633528" | "5639990" |				
		"5640047" | "5641997" | "5643433" |				
		"5644169" | "5646831" | "5650663" |				
		"5661088" | "5663593" | "5665996" |				
		"5673479").PN. OR ("5683806" |				
		"5689135" | "5696666" | "5701034" |				
		"5703407" | "5710064" | "5723899" |				
		"5724233" | "5726493" | "5736432" |				
		"5745984" | "5753532" | "5753977" |				
		"5766972" | "5770888" | "5776798" |				
		"5783861" | "5801440" | "5814877" |				
		"5814881" | "5814883" | "5814884" |				
		"5817540" | "5818105" | "5821457" |				
		"5821615" | "5834830" | "5835988" |				
		"5844306" | "5856911" | "5859471" |				
		"5866939" | "5871782" | "5874784" |				
		"5877043" | "5886397" | "5886398" |				
		"5894108" | "5897339" | "5900676" |				
		"5903049" | "5903050" | "5909053" |				
		"5915998" | "5917242" | "5939779" |				
		"5942794" | "5951305" | "5959356" |				
		"5969426" | "5973388" | "5976912" |				
		"5977613" | "5977615" | "5977630" |				
		"5981314" | "5986333" | "5986885" |				
		"6004761" | "6013947" | "6018189" |				
		"6020625" | "6025640" | "6034279" |				
		"6034423" | "6040626" | "6043430" |				

S60	1	"5594234".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/06 17:26
S61	28	("4714952" | "5252783" | "5428248" | "5436500" | "5440170").PN. OR ("5594234").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/06 20:04
S62	2338	(257/676).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/06 20:05
S63	1330	(257/691).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/06 20:05